

FDI Device Package Certificate of Registration



<u>3-Sci</u> Manufacturer	<u>Wi-Corr Bond</u> Model Name
<u>611A</u> Manufacturer ID (Hex)	<u>E457</u> Device Type (Hex)
<u>0101.fma</u> Device Description File Name	<u>a2e2f276-e764-4b7b-81cd-62547b018c99</u> FDI Device Package ID
<u>3-Sci.Wi- Corr_Bond. 01.01.00.HART.fdx</u> FDI Device Package File Name	<u>01.01.00</u> FDI Package Version
<u>1.2.0</u> FDI Technology Version	<u>L2-06-1000-893.2</u> Registration Number
<u>DPCTT 1.4.2</u> Test System Versions	<u>FieldComm Group Incorporated</u> Registration Authority
<u>No</u> Style Guide Implemented	<u>T. F. Masters</u> Approval
<u>2021-09-29</u> Registration Issue Date	

This document is to certify that the above FDI Package is in conformity with FCG.PD10026 and FCG.PD10028 and meets the requirements to be "REGISTERED".



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